

Welcome to **E-XFL.COM**

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded - Microcontrollers</u>"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	12
Program Memory Size	3KB (2K x 12)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	73 x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	18-SOIC (0.295", 7.50mm Width)
Supplier Device Package	18-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c58b-04e-so

4.4 RC Oscillator

For timing insensitive applications, the RC device option offers additional cost savings. The RC oscillator frequency is a function of the supply voltage, the resistor (REXT) and capacitor (CEXT) values, and the operating temperature. In addition to this, the oscillator frequency will vary from unit to unit due to normal process parameter variation. Furthermore, the difference in lead frame capacitance between package types will also affect the oscillation frequency, especially for low CEXT values. The user also needs to take into account variation due to tolerance of external R and C components used.

Figure 4-5 shows how the R/C combination is connected to the PIC16C5X. For REXT values below 2.2 k Ω , the oscillator operation may become unstable, or stop completely. For very high REXT values (e.g., 1 M Ω) the oscillator becomes sensitive to noise, humidity and leakage. Thus, we recommend keeping REXT between 3 k Ω and 100 k Ω .

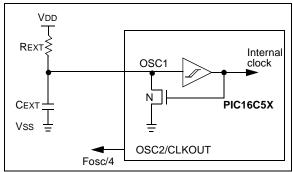
Although the oscillator will operate with no external capacitor (CEXT = 0 pF), we recommend using values above 20 pF for noise and stability reasons. With no or small external capacitance, the oscillation frequency can vary dramatically due to changes in external capacitances, such as PCB trace capacitance or package lead frame capacitance.

The Electrical Specifications sections show RC frequency variation from part to part due to normal process variation. The variation is larger for larger R (since leakage current variation will affect RC frequency more for large R) and for smaller C (since variation of input capacitance will affect RC frequency more).

Also, see the Electrical Specifications sections for variation of oscillator frequency due to VDD for given REXT/CEXT values as well as frequency variation due to operating temperature for given R, C, and VDD values.

The oscillator frequency, divided by 4, is available on the OSC2/CLKOUT pin, and can be used for test purposes or to synchronize other logic.

FIGURE 4-5: RC OSCILLATOR MODE



Note: If you change from this device to another device, please verify oscillator characteristics in your application.

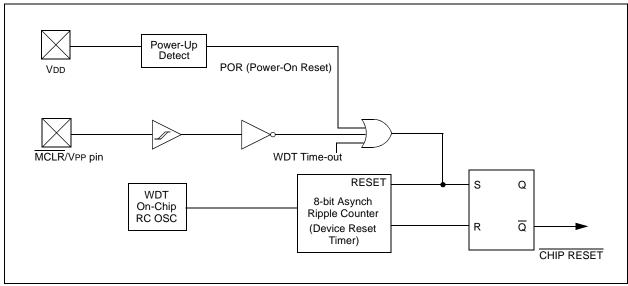
TABLE 5-3: RESET CONDITIONS FOR ALL REGISTERS

Register	Address	Power-On Reset	MCLR or WDT Reset
W	N/A	xxxx xxxx	uuuu uuuu
TRIS	N/A	1111 1111	1111 1111
OPTION	N/A	11 1111	11 1111
INDF	00h	xxxx xxxx	uuuu uuuu
TMR0	01h	xxxx xxxx	uuuu uuuu
PCL	02h	1111 1111	1111 1111
STATUS	03h	0001 1xxx	000q quuu
FSR ⁽¹⁾	04h	1xxx xxxx	luuu uuuu
PORTA	05h	xxxx	uuuu
PORTB	06h	xxxx xxxx	uuuu uuuu
PORTC ⁽²⁾	07h	xxxx xxxx	uuuu uuuu
General Purpose Register Files	07-7Fh	xxxx xxxx	uuuu uuuu

Legend: x = unknown u = unchanged - = unimplemented, read as '0' q = see tables in Table 5-1 for possible values.

2: General purpose register file on PIC16C54/CR54/C56/CR56/C58/CR58.

FIGURE 5-1: SIMPLIFIED BLOCK DIAGRAM OF ON-CHIP RESET CIRCUIT



© 1997-2013 Microchip Technology Inc.

Note 1: These values are valid for PIC16C57/CR57/C58/CR58. For the PIC16C54/CR54/C55/C56/CR56, the value on RESET is 111x xxxx and for MCLR and WDT Reset, the value is 111u uuuu.

TABLE 11-1: DEVELOPMENT TOOLS FROM MICROCHIP

MPLAB® Integrated	> >	> > > > > > >	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	5 5 5 5 5	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	S S S S S S	, , , , , , , , , , , , , , , , , , ,		
MPLAB® C17 C Compiler MPLAB® C18 C Compiler				S S S S S	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \				
MPLAB® C18 C Compiler		\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \		S S S S			
MPASM™ Assembler/ MPLINK™ Object Linker ✓		>> > > >	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	> > > >	> > > >	S S S S			
MPLAB® ICE In-Circuit Emulator	> > > >	> > >	> > > >	\$ \$	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	, , ,	\ \ \ \ \ \		
ICEPIC™ In-Circuit Emulator	> > >	> > >	\ \\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\	\ \ \ \ \ \	\ \ \ \ \ \ \	\	, ,		
MPLAB® ICD In-Circuit Debugger PICSTART® Plus Entry Level Development Programmer PRO MATE® II Universal Device Programmer PICDEM™ 1 Demonstration Board PICDEM™ 2 Demonstration Board PICDEM™ 3 Demonstration Board PICDEM™ 14A Demonstration Board PICDEM™ 14A Demonstration PICDEM™ 15	> >	· · ·	> >	\ \ \ \	> >	, ,	> >		
PICSTART® Plus Entry Level Development Programmer PRO MATE® II Universal Device Programmer PICDEM™ 1 Demonstration Board PICDEM™ 2 Demonstration Board PICDEM™ 3 Demonstration Board PICDEM™ 3 Demonstration Board PICDEM™ 4A Demonstration PICDEM™ 4A Demonstration PICDEM™ 4A Demonstration	> >	> >	> >	> >	> >	, ,	>		
PRO MATE® II Universal Device Programmer PICDEM™ 1 Demonstration Board PICDEM™ 2 Demonstration Board PICDEM™ 3 Demonstration Board PICDEM™ 4A Demonstration Board PICDEM™ 4A Demonstration Board PICDEM™ 4A Demonstration	>	>	>	`	>	``			
W TM 1 Demonstration W TM 2 Demonstration W TM 3 Demonstration					_		`	<u>`</u>	
PICDEM™ 2 Demonstration Board PICDEM™ 3 Demonstration Board PICDEM™ 14A Demonstration	+			>					
PICDEM™ 3 Demonstration Board PICDEM™ 14A Demonstration Board						>	`		
PICDEM™ 14A Demonstration Board			>						
PICDEM™ 17 Demonstration Board					>				
								>	
								>	
microID™ Programmer's Kit									>
5 125 kHz microID™ Developer's Kit									>
125 kHz Anticollision microlD TM Developer's Kit									>
13.56 MHz Anticollision microlD™ Developer's Kit									>
MCP2510 CAN Developer's Kit									

12.1 DC Characteristics: PIC16C54/55/56/57-RC, XT, 10, HS, LP (Commercial)

	54/55/56/ nercial)	57-RC, XT, 10, HS, LP	Standard Operating Conditions (unless otherwise specified) Operating Temperature $0^{\circ}C \le TA \le +70^{\circ}C$ for commercial						
Param No.	Symbol	Characteristic/Device	Min	Тур†	Max	Units	Conditions		
D001	VDD	Supply Voltage PIC16C5X-RC PIC16C5X-XT PIC16C5X-10 PIC16C5X-HS PIC16C5X-LP	3.0 3.0 4.5 4.5 2.5		6.25 6.25 5.5 5.5 6.25	V V V			
D002	Vdr	RAM Data Retention Voltage ⁽¹⁾		1.5*	_	V	Device in SLEEP Mode		
D003	VPOR	VDD Start Voltage to ensure Power-on Reset		Vss	_	V	See Section 5.1 for details on Power-on Reset		
D004	SVDD	VDD Rise Rate to ensure Power-on Reset	0.05*	_	_	V/ms	See Section 5.1 for details on Power-on Reset		
D010	IDD	Supply Current ⁽²⁾ PIC16C5X-RC ⁽³⁾ PIC16C5X-XT PIC16C5X-10 PIC16C5X-HS PIC16C5X-HS PIC16C5X-LP		1.8 1.8 4.8 4.8 9.0	3.3 3.3 10 10 20 32	mA mA mA mA mA	FOSC = 4 MHz, VDD = 5.5V FOSC = 4 MHz, VDD = 5.5V FOSC = 10 MHz, VDD = 5.5V FOSC = 10 MHz, VDD = 5.5V FOSC = 20 MHz, VDD = 5.5V FOSC = 32 kHz, VDD = 3.0V, WDT disabled		
D020	IPD	Power-down Current ⁽²⁾	_	4.0 0.6	12 9	μA μA	VDD = 3.0V, WDT enabled VDD = 3.0V, WDT disabled		

^{*} These parameters are characterized but not tested.

- Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.
 - 2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.
 - a) The test conditions for all IDD measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to Vss, TOCKI = VDD, $\overline{MCLR} = VDD$; WDT enabled/disabled as specified.
 - b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.
 - 3: Does not include current through REXT. The current through the resistor can be estimated by the formula: IR = VDD/2REXT (mA) with REXT in $k\Omega$.

[†] Data in "Typ" column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

TABLE 12-1: EXTERNAL CLOCK TIMING REQUIREMENTS - PIC16C54/55/56/57

AC Characteristics Standard Operating Conditions (unless otherwise specified)
Operating Temperature $0^{\circ}\text{C} \le \text{TA} \le +70^{\circ}\text{C}$ for commercial $-40^{\circ}\text{C} \le \text{TA} \le +85^{\circ}\text{C}$ for industrial $-40^{\circ}\text{C} \le \text{TA} \le +125^{\circ}\text{C}$ for extended

Param No.	Symbol	Characteristic	Min	Typ†	Max	Units	Conditions
1	Tosc	External CLKIN Period ⁽¹⁾	250	_	_	ns	XT osc mode
			100	_	_	ns	10 MHz mode
			50	_	_	ns	HS osc mode (Comm/Ind)
			62.5	_	_	ns	HS osc mode (Ext)
			25	_	_	μS	LP osc mode
		Oscillator Period ⁽¹⁾	250	_	_	ns	RC osc mode
			250	_	10,000	ns	XT osc mode
			100	_	250	ns	10 MHz mode
			50	_	250	ns	HS osc mode (Comm/Ind)
			62.5	_	250	ns	HS osc mode (Ext)
			25	_	_	μS	LP osc mode
2	Tcy	Instruction Cycle Time ⁽²⁾	_	4/Fosc		_	
3	TosL,	Clock in (OSC1) Low or High	85*		_	ns	XT oscillator
	TosH	Time	20*	_	_	ns	HS oscillator
			2.0*	_	_	μS	LP oscillator
4	TosR,	Clock in (OSC1) Rise or Fall	_	_	25*	ns	XT oscillator
	TosF	Time	_	_	25*	ns	HS oscillator
			_		50*	ns	LP oscillator

^{*} These parameters are characterized but not tested.

Note 1: All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. When an external clock input is used, the "max" cycle time limit is "DC" (no clock) for all devices.

2: Instruction cycle period (TcY) equals four times the input oscillator time base period.

[†] Data in the Typical ("Typ") column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

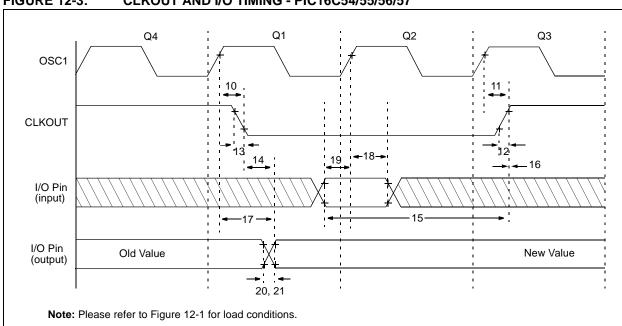


FIGURE 12-3: CLKOUT AND I/O TIMING - PIC16C54/55/56/57

TABLE 12-2: CLKOUT AND I/O TIMING REQUIREMENTS - PIC16C54/55/56/57

AC Chara	acteristics	-40°C ≤ TA ≤ ·	s otherwise spe +70°C for comm +85°C for indust +125°C for exter	ercial rial		
Param No.	Symbol	Characteristic	Min	Тур†	Max	Units
10	TosH2ckL	OSC1↑ to CLKOUT↓ ⁽¹⁾	_	15	30**	ns
11	TosH2ckH	OSC1↑ to CLKOUT↑ ⁽¹⁾	_	15	30**	ns
12	TckR	CLKOUT rise time ⁽¹⁾	_	5.0	15**	ns
13	TckF	CLKOUT fall time ⁽¹⁾	_	5.0	15**	ns
14	TckL2ioV	CLKOUT↓ to Port out valid ⁽¹⁾	_	_	40**	ns
15	TioV2ckH	Port in valid before CLKOUT ⁽¹⁾	0.25 TCY+30*	_	_	ns
16	TckH2ioI	Port in hold after CLKOUT ⁽¹⁾	0*	_	_	ns
17	TosH2ioV	OSC1 [↑] (Q1 cycle) to Port out valid ⁽²⁾	_	_	100*	ns
18	TosH2ioI	OSC1 [↑] (Q2 cycle) to Port input invalid (I/O in hold time)	TBD	_	_	ns
19	TioV2osH	Port input valid to OSC1↑ (I/O in setup time)	TBD		_	ns
20	TioR	Port output rise time ⁽²⁾	_	10	25**	ns
21	TioF	Port output fall time ⁽²⁾	_	10	25**	ns

^{*} These parameters are characterized but not tested.

Note 1: Measurements are taken in RC Mode where CLKOUT output is 4 x Tosc.

2: Please refer to Figure 12-1 for load conditions.

^{**} These parameters are design targets and are not tested. No characterization data available at this time.

[†] Data in the Typical ("Typ") column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

15.1 DC Characteristics: PIC16C54A-04, 10, 20 (Commercial)
PIC16C54A-04I, 10I, 20I (Industrial)
PIC16LC54A-04 (Commercial)
PIC16LC54A-04I (Industrial)

PIC16LC PIC16LC (Comm		ustrial)		ard Ope ting Tem		ire	tions (unless otherwise specified) $0^{\circ}C \le TA \le +70^{\circ}C$ for commercial $40^{\circ}C \le TA \le +85^{\circ}C$ for industrial
PIC16C5	64A-04, 10 64A-04I, 1 ercial, Ind	0I, 20I		ard Ope ting Tem		ire	tions (unless otherwise specified) $0^{\circ}C \le TA \le +70^{\circ}C$ for commercial $40^{\circ}C \le TA \le +85^{\circ}C$ for industrial
Param No.	Symbol	Characteristic/Device	Min	Тур†	Max	Units	Conditions
	VDD	Supply Voltage					
D001		PIC16LC54A	3.0 2.5	_	6.25 6.25	V V	XT and RC modes LP mode
D001A		PIC16C54A	3.0 4.5		6.25 5.5	V V	RC, XT and LP modes HS mode
D002	Vdr	RAM Data Retention Voltage ⁽¹⁾		1.5*	_	>	Device in SLEEP mode
D003	VPOR	VDD Start Voltage to ensure Power-on Reset		Vss	_	V	See Section 5.1 for details on Power-on Reset
D004	SVDD	VDD Rise Rate to ensure Power-on Reset	0.05*	_	_	V/ms	See Section 5.1 for details on Power-on Reset
	IDD	Supply Current ⁽²⁾					
D005		PIC16LC5X	_	0.5	2.5	mA	FOSC = 4.0 MHz, VDD = 5.5V, RC ⁽³⁾ and XT modes
				11	27	μΑ	FOSC = 32 kHz, VDD = 2.5V, WDT disabled, LP mode, Commercial
				11	35	μΑ	FOSC = 32 kHz, VDD = 2.5V, WDT disabled, LP mode, Industrial
D005A		PIC16C5X		1.8	2.4	mA	FOSC = 4.0 MHz, VDD = 5.5V, RC ⁽³⁾ and XT modes
			_	2.4	8.0	mΑ	Fosc = 10 MHz, VDD = 5.5V, HS mode
			_	4.5	16	mΑ	FOSC = 20 MHz, VDD = 5.5V, HS mode
			_	14	29	μΑ	Fosc = 32 kHz, VDD = 3.0V,
			_	17	37	μΑ	WDT disabled, LP mode, Commercial Fosc = 32 kHz, VDD = 3.0V, WDT disabled, LP mode, Industrial

Legend: Rows with standard voltage device data only are shaded for improved readability.

- * These parameters are characterized but not tested.
- † Data in "Typ" column is based on characterization results at 25°C. This data is for design guidance only and is not tested.
- Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.
 - 2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.
 - a) The test conditions for all IDD measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to Vss, T0CKI = VDD, MCLR = VDD; WDT enabled/ disabled as specified.
 - b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.
 - 3: Does not include current through REXT. The current through the resistor can be estimated by the formula: IR = VDD/2REXT (mA) with REXT in $k\Omega$.

15.2 DC Characteristics: PIC16C54A-04E, 10E, 20E (Extended) PIC16LC54A-04E (Extended)

PIC16L	C54A-04E ded)						tions (unless otherwise specified) -40°C \leq TA \leq +125°C for extended	
PIC16C (Extend	•	10E, 20E		ard Ope ting Tem	_		tions (unless otherwise specified) -40 °C \leq TA \leq +125°C for extended	
Param No.	Symbol	Characteristic	Min Typ† Max Units Conditions					
	IPD	Power-down Current ⁽²⁾						
D020		PIC16LC54A		2.5 0.25	15 7.0	μA μA	VDD = 2.5V, WDT enabled, Extended VDD = 2.5V, WDT disabled, Extended	
D020A		PIC16C54A	_	5.0 0.8	22 18*	μ Α μ Α	VDD = 3.5V, WDT enabled VDD = 3.5V, WDT disabled	

- Legend: Rows with standard voltage device data only are shaded for improved readability.
 - * These parameters are characterized but not tested.
 - † Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.
- Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.
 - 2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.
 - a) The test conditions for all IDD measurements in active Operation mode <u>are: OSC1 = external square</u> wave, from rail-to-rail; all I/O pins tristated, pulled to Vss, T0CKI = VDD, MCLR = VDD; WDT enabled/ disabled as specified.
 - b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.
 - 3: Does not include current through REXT. The current through the resistor can be estimated by the formula: IR = VDD/2REXT (mA) with REXT in $k\Omega$.

Timing Parameter Symbology and Load Conditions 15.5

The timing parameter symbols have been created with one of the following formats:

1. TppS2ppS

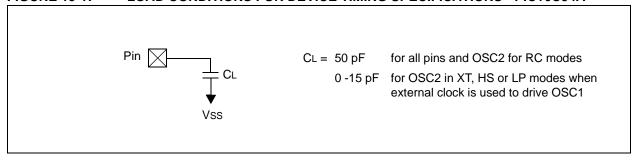
Low

2. TppS

Т		
F	Frequency	T Time
Lowe	ercase letters (pp) and their meanings:	
рр		
2	to	mc MCLR
ck	CLKOUT	osc oscillator
су	cycle time	os OSC1
drt	device reset timer	t0 T0CKI
io	I/O port	wdt watchdog timer
Uppe	ercase letters and their meanings:	
S		
F	Fall	P Period
Н	High	R Rise
I	Invalid (Hi-impedance)	V Valid

Hi-impedance

FIGURE 15-1: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS - PIC16C54A



17.3 DC Characteristics: PIC16C54C/C55A/C56A/C57C/C58B-04, 20 (Commercial, Industrial, Extended)
PIC16LC54C/LC55A/LC56A/LC57C/LC58B-04 (Commercial, Industrial)
PIC16CR54C/CR56A/CR57C/CR58B-04, 20 (Commercial, Industrial, Extended)
PIC16LCR54C/LCR56A/LCR57C/LCR58B-04 (Commercial, Industrial)

DC CH	ARACTE	RISTICS	Standard Operating Conditions (unless otherwise specified) Operating Temperature $0^{\circ}C \leq TA \leq +70^{\circ}C$ for commercial $-40^{\circ}C \leq TA \leq +85^{\circ}C$ for industrial $-40^{\circ}C \leq TA \leq +125^{\circ}C$ for extended						
Param No.	Symbol	Characteristic	Min	Тур†	Max	Units	Conditions		
D030	VIL	Input Low Voltage I/O Ports I/O Ports MCLR (Schmitt Trigger) T0CKI (Schmitt Trigger) OSC1 (Schmitt Trigger) OSC1	Vss Vss Vss Vss Vss	_ _ _ _	0.8 V 0.15 VDD 0.15 VDD 0.15 VDD 0.15 VDD 0.3 VDD	V V V V	4.5V <vdd 5.5v="" mode="" only<sup="" otherwise="" rc="" ≤="">(3) XT, HS and LP modes</vdd>		
D040	ViH	Input High Voltage I/O ports I/O ports MCLR (Schmitt Trigger) T0CKI (Schmitt Trigger) OSC1 (Schmitt Trigger) OSC1	2.0 0.25 Vdd+0.8 0.85 Vdd 0.85 Vdd 0.85 Vdd 0.7 Vdd	_ _ _ _	VDD VDD VDD VDD VDD VDD	V V V V	4.5V < VDD ≤ 5.5V Otherwise RC mode only ⁽³⁾ XT, HS and LP modes		
D050	VHYS	Hysteresis of Schmitt Trigger inputs	0.15 VDD*	_	_	V			
D060	lı∟	Input Leakage Current ^(1,2) I/O ports	-1.0	0.5	+1.0	μΑ	For VDD ≤ 5.5V: VSS ≤ VPIN ≤ VDD, pin at hi-impedance		
		MCLR MCLR TOCKI OSC1	-5.0 -3.0 -3.0	0.5 0.5 0.5	+5.0 +3.0 +3.0 —	μΑ μΑ μΑ μΑ	VPIN = VSS +0.25V VPIN = VDD VSS ≤ VPIN ≤ VDD VSS ≤ VPIN ≤ VDD, XT, HS and LP modes		
D080	Vol	Output Low Voltage I/O ports OSC2/CLKOUT		_	0.6 0.6	V V	IOL = 8.7 mA, VDD = 4.5V IOL = 1.6 mA, VDD = 4.5V, RC mode only		
D090	Voн	Output High Voltage ⁽²⁾ I/O ports OSC2/CLKOUT	VDD - 0.7 VDD - 0.7	_		V V	IOH = -5.4 mA, VDD = 4.5V IOH = -1.0 mA, VDD = 4.5V, RC mode only		

These parameters are characterized but not tested.

[†] Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: The leakage current on the MCLR/VPP pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltage.

^{2:} Negative current is defined as coming out of the pin.

^{3:} For the RC mode, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C5X be driven with external clock in RC mode.

17.5 Timing Diagrams and Specifications

FIGURE 17-6: EXTERNAL CLOCK TIMING - PIC16C5X, PIC16CR5X

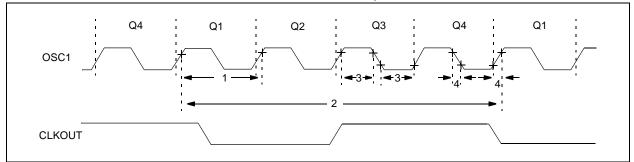


TABLE 17-1: EXTERNAL CLOCK TIMING REQUIREMENTS - PIC16C5X, PIC16CR5X

AC Characteristics Standard Operating Conditions (unless otherwise specified)
Operating Temperature $0^{\circ}C \le TA \le +70^{\circ}C$ for commercial $-40^{\circ}C \le TA \le +85^{\circ}C$ for industrial $-40^{\circ}C \le TA \le +125^{\circ}C$ for extended

Param No.	Symbol	Characteristic	Min	Тур†	Мах	Units	Conditions
	Fosc	External CLKIN Frequency ⁽¹⁾	DC	_	4.0	MHz	XT osc mode
			DC	_	4.0	MHz	HS osc mode (04)
			DC	_	20	MHz	HS osc mode (20)
			DC	_	200	kHz	LP osc mode
		Oscillator Frequency ⁽¹⁾	DC	_	4.0	MHz	RC osc mode
			0.45	_	4.0	MHz	XT osc mode
			4.0	_	4.0	MHz	HS osc mode (04)
			4.0	_	20	MHz	HS osc mode (20)
			5.0	_	200	kHz	LP osc mode
1	Tosc	External CLKIN Period ⁽¹⁾	250	_	_	ns	XT osc mode
			250	_	_	ns	HS osc mode (04)
			50	_		ns	HS osc mode (20)
			5.0	_		μS	LP osc mode
		Oscillator Period ⁽¹⁾	250	_	_	ns	RC osc mode
			250	_	2,200	ns	XT osc mode
			250	_	250	ns	HS osc mode (04)
			50	_	250	ns	HS osc mode (20)
			5.0	_	200	μS	LP osc mode

^{*} These parameters are characterized but not tested.

[†] Data in the Typical ("Typ") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption.

When an external clock input is used, the "max" cycle time limit is "DC" (no clock) for all devices.

^{2:} Instruction cycle period (TCY) equals four times the input oscillator time base period.

FIGURE 17-8: RESET, WATCHDOG TIMER, AND DEVICE RESET TIMER TIMING - PIC16C5X, PIC16CR5X

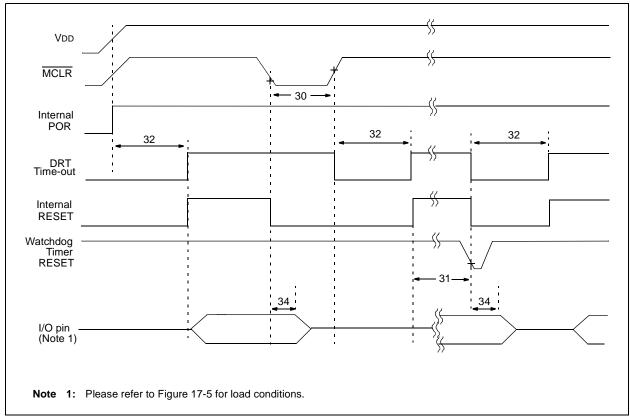


TABLE 17-3: RESET, WATCHDOG TIMER, AND DEVICE RESET TIMER - PIC16C5X, PIC16CR5X

AC Charac	teristics	Standard Operating Conditions (L Operating Temperature $0^{\circ}C \le -40^{\circ}C \le $	$TA \le +7$ $TA \le +8$	0°C for 5°C for	commei industria	rcial al	
Param No.				Тур†	Max	Units	Conditions
30	TmcL	MCLR Pulse Width (low)	1000*	_	_	ns	VDD = 5.0V
31	Twdt	Watchdog Timer Time-out Period (No Prescaler)	9.0*	18*	30*	ms	VDD = 5.0V (Comm)
32	TDRT	Device Reset Timer Period	9.0*	18*	30*	ms	VDD = 5.0V (Comm)
34	Tioz	I/O Hi-impedance from MCLR Low	100*	300*	1000*	ns	

^{*} These parameters are characterized but not tested.

[†] Data in the Typical ("Typ") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 18-6: TYPICAL IPD vs. VDD, WATCHDOG ENABLED (25°C)

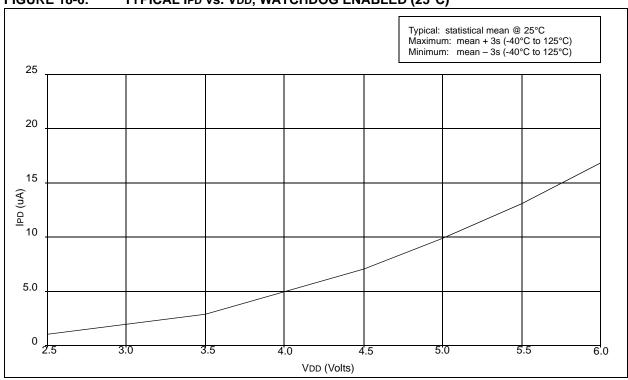
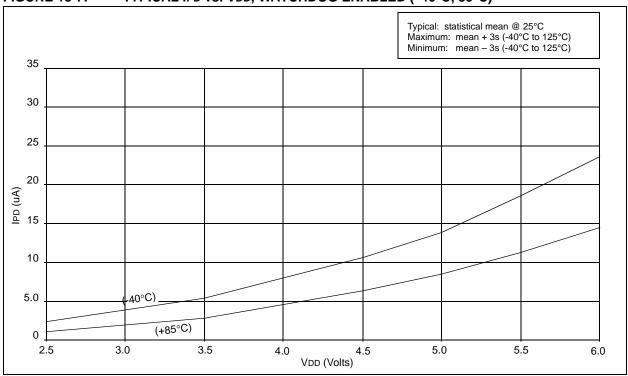


FIGURE 18-7: TYPICAL IPD vs. VDD, WATCHDOG ENABLED (-40°C, 85°C)



19.3 Timing Parameter Symbology and Load Conditions

The timing parameter symbols have been created with one of the following formats:

- 1. TppS2ppS
- 2. TppS

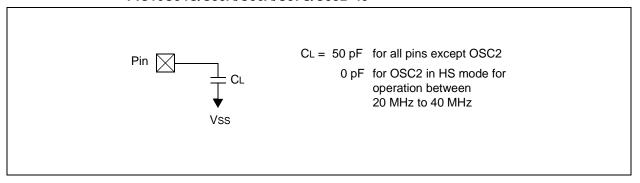
T	
F Frequency	T Time
Lowercase letters (pp) and their meanings:	
рр	
2 40	ma MOLD

pp		
2	to	mc MCLR
ck	CLKOUT	osc oscillator
су	cycle time	os OSC1
drt	device reset timer	t0 T0CKI
io	I/O port	wdt watchdog timer

Uppercase letters and their meanings:

	orease letters and tron meanings.		
S			
F	Fall	Р	Period
Н	High	R	Rise
1	Invalid (Hi-impedance)	V	Valid
L	Low	Z	Hi-impedance

FIGURE 19-2: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS - PIC16C54C/C55A/C56A/C57C/C58B-40



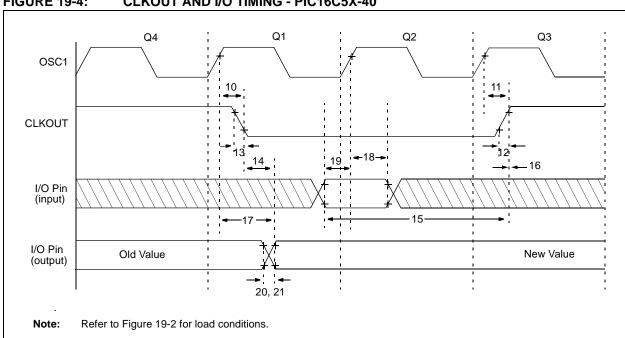


FIGURE 19-4: CLKOUT AND I/O TIMING - PIC16C5X-40

CLKOUT AND I/O TIMING REQUIREMENTS - PIC16C5X-40 TABLE 19-2:

AC Chara	acteristics	Standard Operating Conditions (unless otherwise specified) Operating Temperature $0^{\circ}C \le TA \le +70^{\circ}C$ for commercial							
Param No.	Symbol	Characteristic	Min	Тур†	Max	Units			
10	TosH2ckL	OSC1↑ to CLKOUT↓ ^(1,2)	_	15	30**	ns			
11	TosH2ckH	OSC1↑ to CLKOUT↑ ^(1,2)	_	15	30**	ns			
12	TckR	CLKOUT rise time ^(1,2)	_	5.0	15**	ns			
13	TckF	CLKOUT fall time ^(1,2)	_	5.0	15**	ns			
14	TckL2ioV	CLKOUT↓ to Port out valid ^(1,2)	_	_	40**	ns			
15	TioV2ckH	Port in valid before CLKOUT ^(1,2)	0.25 TCY+30*	_	_	ns			
16	TckH2iol	Port in hold after CLKOUT ^(1,2)	0*	_	_	ns			
17	TosH2ioV	OSC1 [↑] (Q1 cycle) to Port out valid ⁽²⁾	_	_	100	ns			
18	TosH2iol	OSC1 [↑] (Q2 cycle) to Port input invalid (I/O in hold time)	TBD	_	_	ns			
19	TioV2osH	Port input valid to OSC1↑ (I/O in setup time)	TBD	_	_	ns			
20	TioR	Port output rise time ⁽²⁾	_	10	25**	ns			
21	TioF	Port output fall time ⁽²⁾	_	10	25**	ns			

These parameters are characterized but not tested.

Note 1: Measurements are taken in RC Mode where CLKOUT output is 4 x Tosc.

2: Refer to Figure 19-2 for load conditions.

These parameters are design targets and are not tested. No characterization data available at this time.

Data in the Typical ("Typ") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 19-6: TIMERO CLOCK TIMINGS - PIC16C5X-40

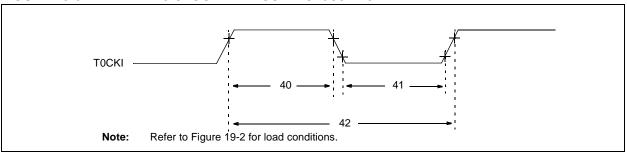


TABLE 19-4: TIMERO CLOCK REQUIREMENTS PIC16C5X-40

A	AC Charac	TERISTICS	Standard Operating Conditions (unless otherwise specified) Operating Temperature $0^{\circ}C \le TA \le +70^{\circ}C$ for commercial					
Param No.	Symbol	Characteristic	Min	Тур†	Max	Units	Conditions	
40	Tt0H	T0CKI High Pulse Width - No Prescaler	0.5 Tcy + 20*			ns		
		- With Prescaler	10*	_	—	ns		
41	TtOL	T0CKI Low Pulse Width - No Prescaler	0.5 Tcy + 20*	_	_	ns		
		- With Prescaler	10*	_	—	ns		
42	Tt0P	T0CKI Period	20 or <u>Tcy + 40</u> * N	_	_	ns	Whichever is greater. N = Prescale Value (1, 2, 4,, 256)	

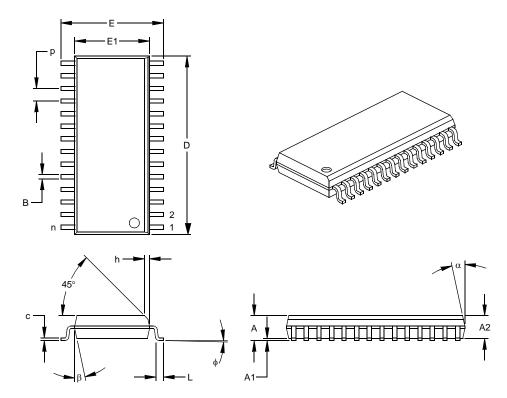
^{*} These parameters are characterized but not tested.

[†] Data in the Typical ("Typ") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

28-Lead Plastic Small Outline (SO) - Wide, 300 mil (SOIC)

Note:

For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	INCHES*			MILLIMETERS			
Dimension	Limits	MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		28			28	
Pitch	р		.050			1.27	
Overall Height	Α	.093	.099	.104	2.36	2.50	2.64
Molded Package Thickness	A2	.088	.091	.094	2.24	2.31	2.39
Standoff §	A1	.004	.008	.012	0.10	0.20	0.30
Overall Width	Е	.394	.407	.420	10.01	10.34	10.67
Molded Package Width	E1	.288	.295	.299	7.32	7.49	7.59
Overall Length	D	.695	.704	.712	17.65	17.87	18.08
Chamfer Distance	h	.010	.020	.029	0.25	0.50	0.74
Foot Length	L	.016	.033	.050	0.41	0.84	1.27
Foot Angle Top	ф	0	4	8	0	4	8
Lead Thickness	С	.009	.011	.013	0.23	0.28	0.33
Lead Width	В	.014	.017	.020	0.36	0.42	0.51
Mold Draft Angle Top	α	0	12	15	0	12	15
Mold Draft Angle Bottom	β	0	12	15	0	12	15

Notes:

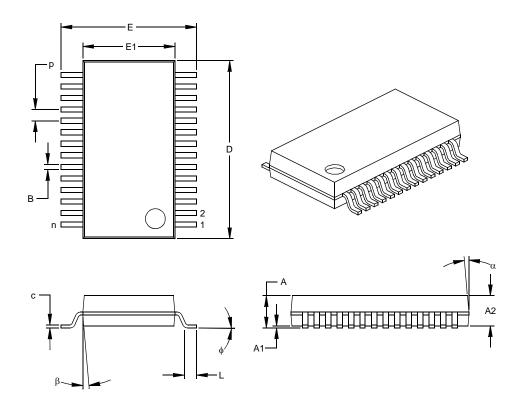
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed

.010" (0.254mm) per side. JEDEC Equivalent: MS-013 Drawing No. C04-052

^{*} Controlling Parameter § Significant Characteristic

28-Lead Plastic Shrink Small Outline (SS) - 209 mil, 5.30 mm (SSOP)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units	INCHES			MILLIMETERS*		
Dimension	Limits	MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		28			28	
Pitch	р		.026			0.65	
Overall Height	Α	.068	.073	.078	1.73	1.85	1.98
Molded Package Thickness	A2	.064	.068	.072	1.63	1.73	1.83
Standoff §	A1	.002	.006	.010	0.05	0.15	0.25
Overall Width	Е	.299	.309	.319	7.59	7.85	8.10
Molded Package Width	E1	.201	.207	.212	5.11	5.25	5.38
Overall Length	D	.396	.402	.407	10.06	10.20	10.34
Foot Length	L	.022	.030	.037	0.56	0.75	0.94
Lead Thickness	С	.004	.007	.010	0.10	0.18	0.25
Foot Angle	ф	0	4	8	0.00	101.60	203.20
Lead Width	В	.010	.013	.015	0.25	0.32	0.38
Mold Draft Angle Top	α	0	5	10	0	5	10
Mold Draft Angle Bottom	β	0	5	10	0	5	10

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

JEDEC Equivalent: MS-150 Drawing No. C04-073

^{*} Controlling Parameter § Significant Characteristic

PIC16C5X

M	Q
MCLR Reset	Q cycles
Register values on20	Quick-Turnaround-Production (QTP) Devices
Memory Map	(4) =
PIC16C54/CR54/C5525	R
PIC16C56/CR5625	RC Oscillator17
PIC16C57/CR57/C58/CR5825	Read Only Memory (ROM) Devices7
Memory Organization25	Read-Modify-Write
MOVF56	Register File Map
MOVLW56	PIC16C54, PIC16CR54, PIC16C55, PIC16C56,
MOVWF57	PIC16CR56
MPLAB C17 and MPLAB C18 C Compilers61	PIC16C57/CR5727
MPLAB ICD In-Circuit Debugger63	PIC16C58/CR5827
MPLAB ICE High Performance Universal In-Circuit Emulator	Registers
with MPLAB IDE62	Special Function
MPLAB Integrated Development Environment Software 61	Value on reset
MPLINK Object Linker/MPLIB Object Librarian62	Reset
NI .	Reset on Brown-Out23
N	RETLW 57
NOP57	RLF58
•	RRF 58
0	0
One-Time-Programmable (OTP) Devices7	S
OPTION57	Serialized Quick-Turnaround-Production (SQTP) Devices 7
OPTION Register30	SLEEP 43, 47, 58
Value on reset20	Software Simulator (MPLAB SIM)62
Oscillator Configurations15	Special Features of the CPU43
Oscillator Types	Special Function Registers
HS15	Stack
LP15	STATUS Register
RC15	Value on reset20
XT15	SUBWF59
P	SWAPF59
	Т
PA0 bit	•
PA1 bit	Timer0
Paging31	Switching Prescaler Assignment
PC	Timer0 (TMR0) Module
Value on reset	TMR0 register - Value on reset
PD bit	TMR0 with External Clock
Peripheral Features	Timing Diagrams and Specifications
PICDEM 1 Low Cost PIC MCU Demonstration Board63	PIC16C54/55/56/57
PICDEM 17 Demonstration Board	
	PIC16C54C/CR54C/C55A/C56A/CR56A/C57C/CR57C/
PICCEA BT Divis February Levis Device	C58B/CR58B
PICSTART Plus Entry Level Development Programmer 63	PIC16C54C/CR54C/C55A/C56A/CR56A/C57C/CR57C/
Pin Configurations 2	C58B/CR58B-40
Pinout Description - PIC16C54, PIC16CR54, PIC16C56,	PIC16CR54A
PIC16CR56, PIC16C58, PIC16CR5811 Pinout Description - PIC16C55, PIC16C57, PIC16CR5712	Timing Parameter Symbology and Load Conditions
PORTA	PIC16C54/55/56/57
Value on reset	PIC16C54C/CR54C/C55A/C56A/CR56A/C57C/CR57C/
PORTB	C58B/CR58B139
	PIC16C54C/CR54C/C55A/C56A/CR56A/C57C/CR57C/
Value on reset	C58B/CR58B-40159
Value on reset 20	PIC16CR54A
Power-Down Mode	TO bit
Power-On Reset (POR)	TRIS
Register values on	TRIS Registers
Prescaler	Value on reset
PRO MATE II Universal Device Programmer	value on reset
Program Counter	U
Program Memory Organization	UV Erasable Devices7
Program Verification/Code Protection	5 - E100000 5011000
<u> </u>	

ON-LINE SUPPORT

Microchip provides on-line support on the Microchip World Wide Web (WWW) site.

The web site is used by Microchip as a means to make files and information easily available to customers. To view the site, the user must have access to the Internet and a web browser, such as Netscape or Microsoft Explorer. Files are also available for FTP download from our FTP site.

Connecting to the Microchip Internet Web Site

The Microchip web site is available by using your favorite Internet browser to attach to:

www.microchip.com

The file transfer site is available by using an FTP service to connect to:

ftp://ftp.microchip.com

The web site and file transfer site provide a variety of services. Users may download files for the latest Development Tools, Data Sheets, Application Notes, User's Guides, Articles and Sample Programs. A variety of Microchip specific business information is also available, including listings of Microchip sales offices, distributors and factory representatives. Other data available for consideration is:

- Latest Microchip Press Releases
- Technical Support Section with Frequently Asked Questions
- · Design Tips
- Device Errata
- · Job Postings
- Microchip Consultant Program Member Listing
- Links to other useful web sites related to Microchip Products
- Conferences for products, Development Systems, technical information and more
- · Listing of seminars and events